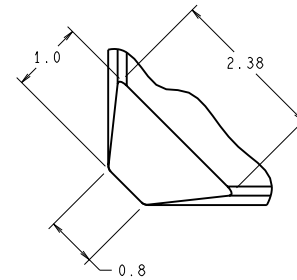
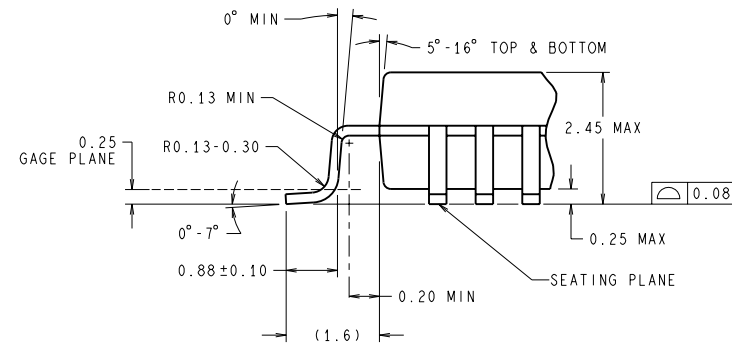


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE AND REDRAW PER JEDEC MS-022.	11042	07/24/95	DEG/



OPTIONAL PIN 1 CORNER  
SCALE: 21X



DETAIL A  
TYP, SCALE: 17X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.  
ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.15mm.
- REFERENCE JEDEC STANDARD MS-022, VARIATION BB,  
DATED FEB/95.

APPROVALS		DATE	 2900 Semiconductor dr., Santa Clara, CA 95052-8090 PQFP, JEDEC METRIC, (S), 14 X 14 X 2.0mm, 64 LEAD		
DRAWN	<i>D. E. Grady</i>	07/24/95			
DFTG. CHK.					
ENGR. CHK.					
 INCH (MM)		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VJQ64A	C
DO NOT SCALE DRAWING				SHEET 1 of 1	